

CD4070B, CD4077B

CMOS Quad Exclusive-OR and Exclusive-NOR Gate

Features

- High-Voltage Types (20V Rating)
- CD4070B - Quad Exclusive-OR Gate
- CD4077B - Quad Exclusive-NOR Gate
- Medium Speed Operation
 - $t_{PHL}, t_{PLH} = 65\text{ns}$ (Typ) at $V_{DD} = 10\text{V}$, $C_L = 50\text{pF}$
- 100% Tested for Quiescent Current at 20V
- Standardized Symmetrical Output Characteristics
- 5V, 10V and 15V Parametric Ratings
- Maximum Input Current of $1\mu\text{A}$ at 18V Over Full Package Temperature Range
 - 100nA at 18V and 25°C
- Noise Margin (Over Full Package Temperature Range)
 - 1V at $V_{DD} = 5\text{V}$, 2V at $V_{DD} = 10\text{V}$, 2.5V at $V_{DD} = 15\text{V}$
- Meets All Requirements of JEDEC Standard No. 13B, "Standard Specifications for Description of 'B' Series CMOS Devices"

Applications

- Logical Comparators
- Adders/Subtractors
- Parity Generators and Checkers

Description

The Harris CD4070B contains four independent Exclusive-OR gates. The Harris CD4077B contains four independent Exclusive-NOR gates.

The CD4070B and CD4077B provide the system designer with a means for direct implementation of the Exclusive-OR and Exclusive-NOR functions, respectively.

Ordering Information

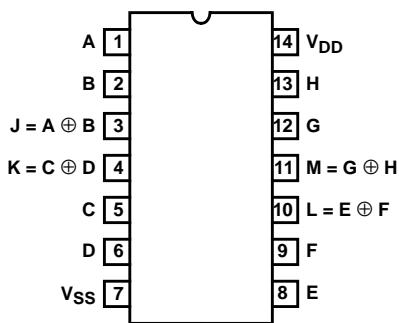
PART NUMBER	TEMP. RANGE (°C)	PACKAGE
CD4070BE	-55 to 125	14 Ld PDIP
CD4070BF3A	-55 to 125	14 Ld CERDIP
CD4070BM	-55 to 125	14 Ld SOIC
CD4070BMT	-55 to 125	14 Ld SOIC
CD4070BM96	-55 to 125	14 Ld SOIC
CD4070BNSR	-55 to 125	14 Ld SOP
CD4070BPW	-55 to 125	14 Ld TSSOP
CD4070BPWR	-55 to 125	14 Ld TSSOP
CD4077BE	-55 to 125	14 Ld PDIP
CD4077BF3A	-55 to 125	14 Ld CERDIP
CD4077BM	-55 to 125	14 Ld SOIC
CD4077BMT	-55 to 125	14 Ld SOIC
CD4077BM96	-55 to 125	14 Ld SOIC
CD4077BNSR	-55 to 125	14 Ld SOP
CD4077BPW	-55 to 125	14 Ld TSSOP
CD4077BPWR	-55 to 125	14 Ld TSSOP

NOTE: When ordering, use the entire part number. The suffixes 96 and R denote tape and reel. The suffix T denotes a small-quantity reel of 250.

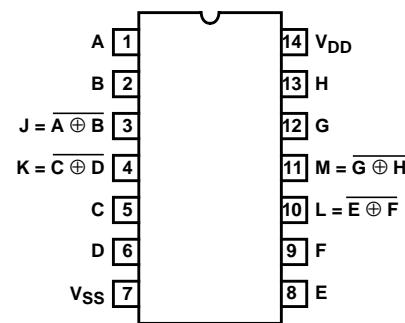
CD4070B, CD4077B

Pinouts

CD4070B
(PDIP, CERDIP, SOIC, SOP, TSSOP)
TOP VIEW

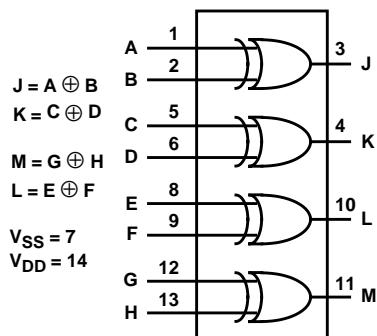


CD4077B
(PDIP, CERDIP, SOIC, SOP, TSSOP)
TOP VIEW

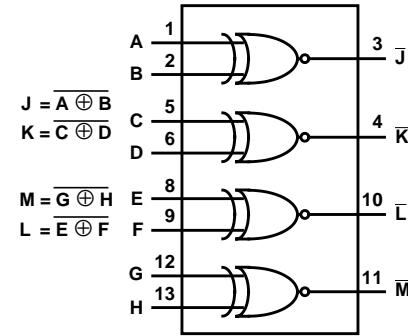


Functional Diagrams

CD4070B



CD4077B



CD4070B, CD4077B

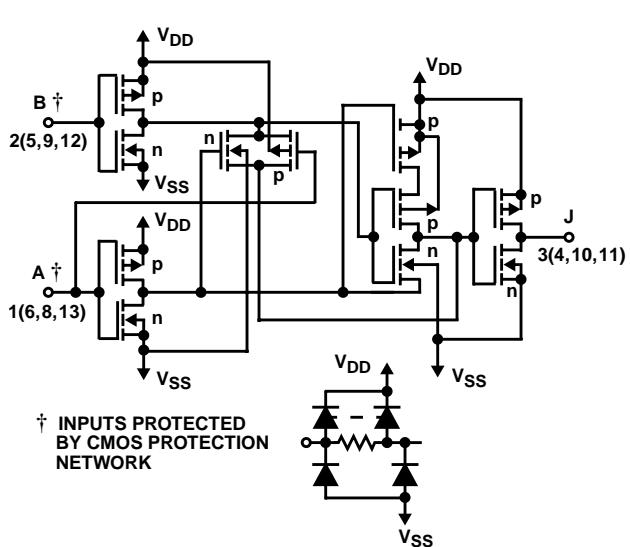


FIGURE 1. SCHEMATIC DIAGRAM FOR CD4070B
(1 OF 4 IDENTICAL GATES)

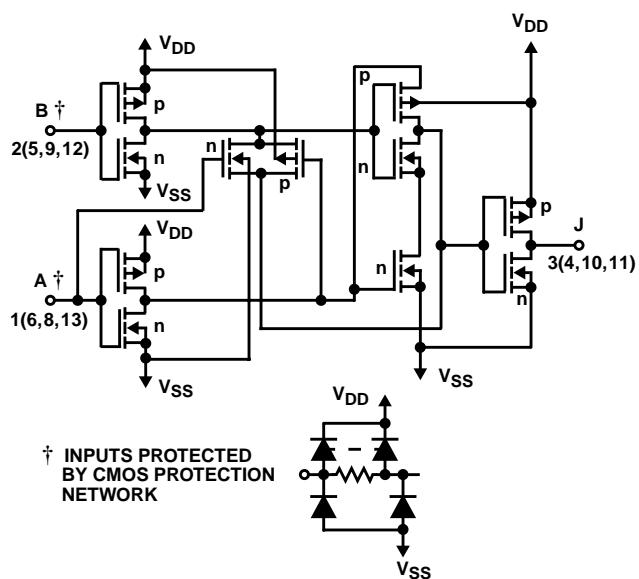


FIGURE 2. SCHEMATIC DIAGRAM FOR CD4077B
(1 OF 4 IDENTICAL GATES)

CD4070B TRUTH TABLE (1 OF 4 GATES)

A	B	J
0	0	0
1	0	1
0	1	1
1	1	0

NOTE:

1 = High Level

0 = Low Level

J = A \oplus B

CD4077B TRUTH TABLE (1 OF 4 GATES)

A	B	J
0	0	1
1	0	0
0	1	0
1	1	1

NOTE:

1 = High Level

0 = Low Level

J = A \oplus B

Absolute Maximum Ratings

DC Supply Voltage Range (V_{DD}) -0.5V to 20V
 Input Voltage Range, All Inputs -0.5V to V_{DD} 0.5V
 DC Input Current $\pm 10\text{mA}$

Operating Conditions

Temperature Range (T_A) -55°C to 125°C
 Supply Voltage Range (Typical) 3V to 18V

Thermal Information

Package Thermal Impedance, θ_{JA} (see Note 1):		
E (PDIP) Package	80°C/W
M (SOIC) Package	86°C/W
NS (SOP) Package	76°C/W
PW (TSSOP) Package	113°C/W
Maximum Junction Temperature (Hermetic Package or Die)	175°C
Maximum Junction Temperature (Plastic Package)	150°C
Maximum Storage Temperature Range	-65°C to 150°C

CAUTION: Stresses above those listed in "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress only rating and operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied.

NOTE:

1. The package thermal impedance is calculated in accordance with JESD 51-7.

DC Electrical Specifications

PARAMETER	CONDITIONS			LIMITS AT INDICATED TEMPERATURES (°C)						UNITS
				-55	-40	85	125	25		
	V_O (V)	V_{IN} (V)	V_{DD} (V)	MIN	TYP	MAX				
Quiescent Device Current I_{DD} Max	-	0, 5	5	0.25	0.25	7.5	7.5	-	0.01	0.25
	-	0, 10	10	0.5	0.5	15	15	-	0.01	0.5
	-	0, 15	15	1	1	30	30	-	0.01	1
	-	0, 20	20	5	5	150	150	-	0.02	5
Output Low (Sink) Current I_{OL} Min	0.4	0, 5	5	0.64	0.61	0.42	0.36	0.51	1	-
	0.5	0, 10	10	1.6	1.5	1.1	0.9	1.3	2.6	-
	1.5	0, 15	15	4.2	4	2.8	2.4	3.4	6.8	-
Output High (Source) Current I_{OH} Min	4.6	0, 5	5	-0.64	-0.61	-0.42	-0.36	-0.51	-1	-
	2.5	0, 5	5	-2	-1.8	-1.3	-1.15	-1.6	-3.2	-
	9.5	0, 10	10	-1.6	-1.5	-1.1	-0.9	-1.3	-2.6	-
	13.5	0, 15	15	-4.2	-4	-2.8	-2.4	-3.4	-6.8	-
Output Voltage: Low Level, V_{OL} Max	-	0, 5	5	0.05	0.05	0.05	0.05	-	0	0.05
	-	0, 10	10	0.05	0.05	0.05	0.05	-	0	0.05
	-	0, 15	15	0.05	0.05	0.05	0.05	-	0	0.05
Output Voltage: High Level, V_{OH} Min	-	0, 5	5	4.95	4.95	4.95	4.95	4.95	5	-
	-	0, 10	10	9.95	9.95	9.95	9.95	9.95	10	-
	-	0, 15	15	14.95	14.95	14.95	14.95	14.95	15	-
Input Low Voltage, V_{IL} Max	0.5, 4.5	-	5	1.5	1.5	1.5	1.5	-	-	1.5
	1, 9	-	10	3	3	3	3	-	-	3
	1.5, 13.5	-	15	4	4	4	4	-	-	4
Input High Voltage, V_{IH} Min	0.5, 4.5	-	5	3.5	3.5	3.5	3.5	-	-	V
	1, 9	-	10	7	7	7	7	-	-	V
	1.5, 13.5	-	15	11	11	11	11	-	-	V
Input Current, I_{IN} Max	-	0, 18	18	± 0.1	± 0.1	± 1	± 1	-	$\pm 10^{-5}$	± 0.1

AC Electrical Specifications $T_A = 25^\circ\text{C}$, Input $t_r, t_f = 20\text{ns}$, $C_L = 50\text{pF}$, $R_L = 200\text{k}\Omega$

PARAMETER	SYMBOL	TEST CONDITIONS		LIMITS ON ALL TYPES		UNITS
		V_{DD} (V)	TYP	MAX		
Propagation Delay Time	t_{PHL}, t_{PLH}	5	140	280	ns	
		10	65	130	ns	
		15	50	100	ns	
Transition Time	t_{THL}, t_{TLH}	5	100	200	ns	
		10	50	100	ns	
		15	40	80	ns	
Input Capacitance	C_{IN}	Any Input	5	7.5	pF	

Typical Performance Curves

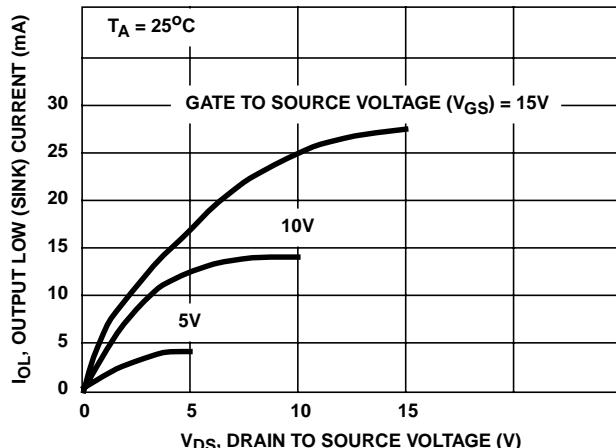


FIGURE 3. TYPICAL OUTPUT LOW (SINK) CURRENT CHARACTERISTICS

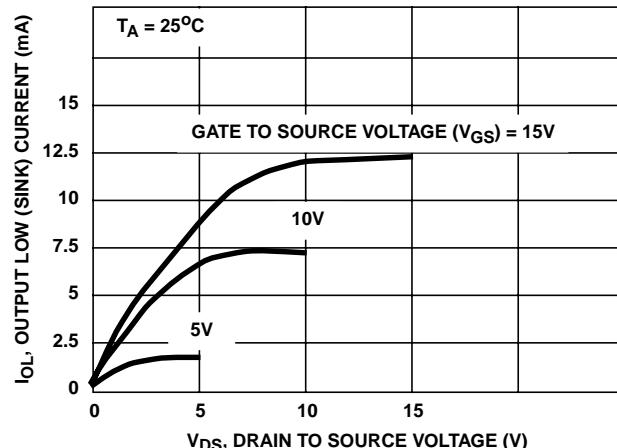


FIGURE 4. MINIMUM OUTPUT LOW (SINK) CURRENT CHARACTERISTICS

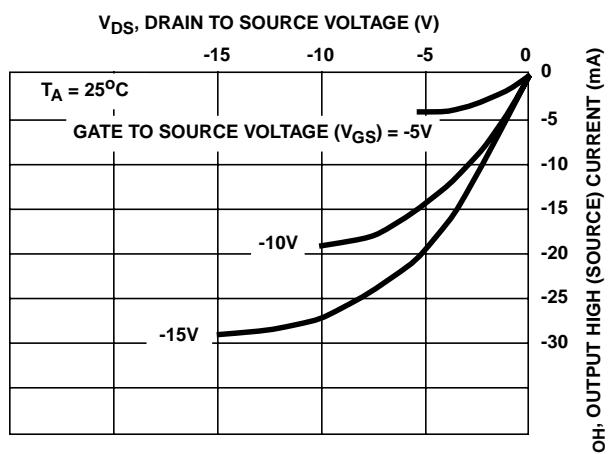


FIGURE 5. TYPICAL OUTPUT HIGH (SOURCE) CURRENT CHARACTERISTICS

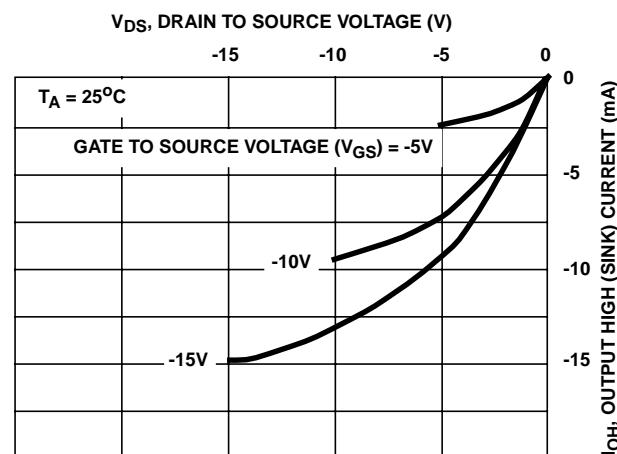


FIGURE 6. MINIMUM OUTPUT HIGH (SOURCE) CURRENT CHARACTERISTICS

Typical Performance Curves (Continued)

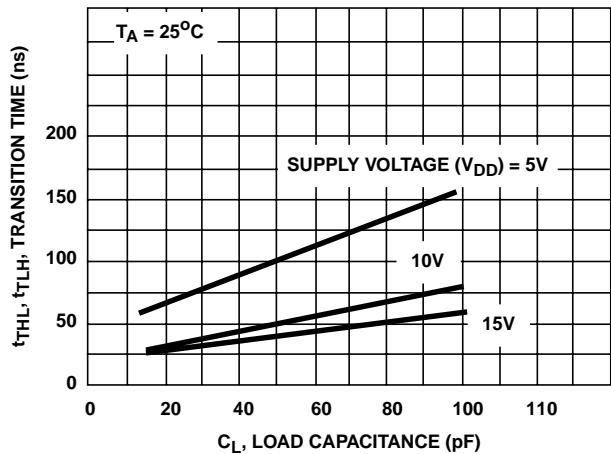


FIGURE 7. TYPICAL TRANSITION TIME AS A FUNCTION OF LOAD CAPACITANCE

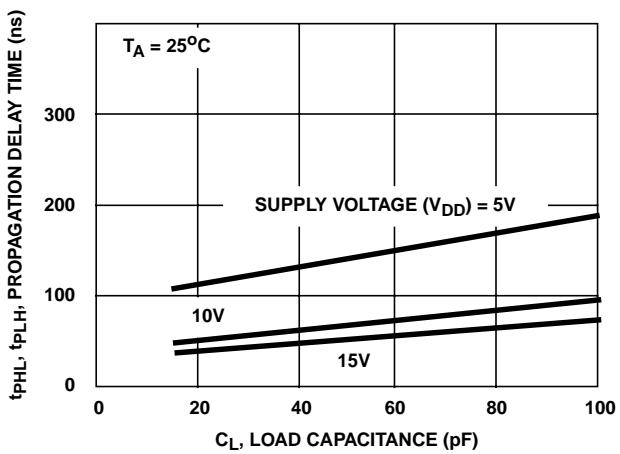


FIGURE 8. TYPICAL PROPAGATION DELAY TIME AS A FUNCTION OF LOAD CAPACITANCE

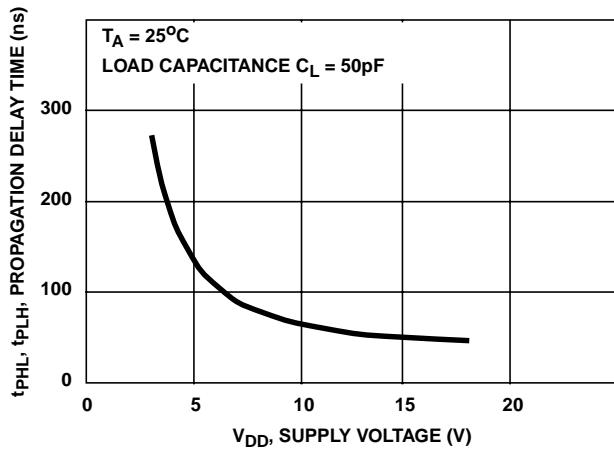


FIGURE 9. TYPICAL PROPAGATION DELAY TIME AS A FUNCTION OF SUPPLY VOLTAGE

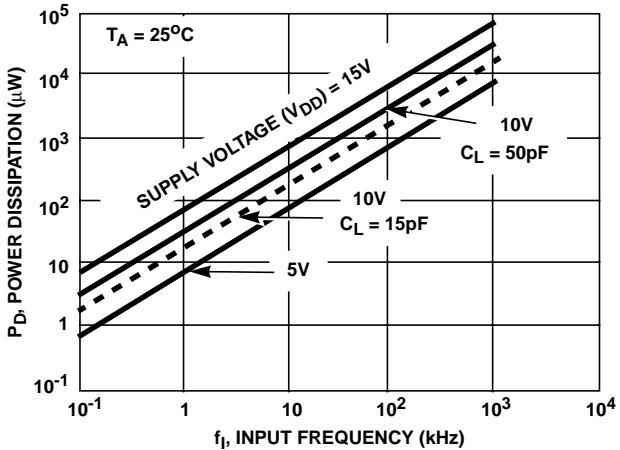


FIGURE 10. TYPICAL DYNAMIC POWER DISSIPATION AS A FUNCTION OF INPUT FREQUENCY

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
CD4070BE	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
CD4070BEE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
CD4070BF	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type
CD4070BF3A	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type
CD4070BF3AS2534	OBsolete	CDIP	J	14		TBD	Call TI	Call TI
CD4070BM	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD4070BM96	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD4070BM96E4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD4070BM96G4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD4070BME4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD4070BMG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD4070BMT	ACTIVE	SOIC	D	14	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD4070BMTE4	ACTIVE	SOIC	D	14	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD4070BMTG4	ACTIVE	SOIC	D	14	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD4070BNSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD4070BNSRE4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD4070BNSRG4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD4070BPW	ACTIVE	TSSOP	PW	14	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD4070BPWE4	ACTIVE	TSSOP	PW	14	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD4070BPWG4	ACTIVE	TSSOP	PW	14	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD4070BPWR	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD4070BPWRE4	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD4070BPWRG4	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD4077BE	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
CD4077BEE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
CD4077BF	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type
CD4077BF3A	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
CD4077BM	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD4077BM96	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD4077BM96E4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD4077BM96G4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD4077BME4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD4077BMG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD4077BMT	ACTIVE	SOIC	D	14	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD4077BMTE4	ACTIVE	SOIC	D	14	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD4077BMTG4	ACTIVE	SOIC	D	14	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD4077BNSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD4077BNSRE4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD4077BNSRG4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD4077BPW	ACTIVE	TSSOP	PW	14	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD4077BPWE4	ACTIVE	TSSOP	PW	14	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD4077BPWG4	ACTIVE	TSSOP	PW	14	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD4077BPWR	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD4077BPWRE4	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD4077BPWRG4	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
JM38510/17203BCA	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS

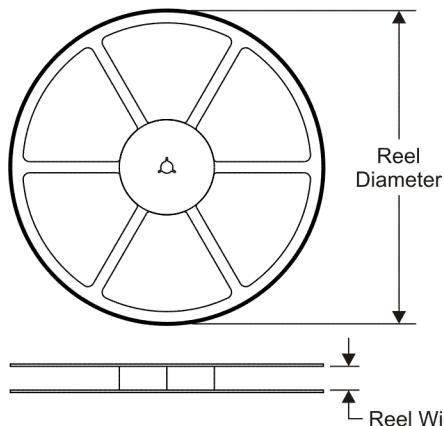
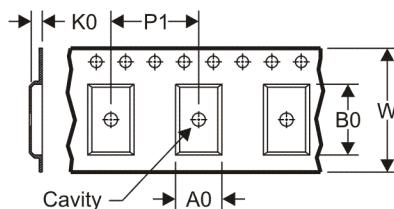
compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

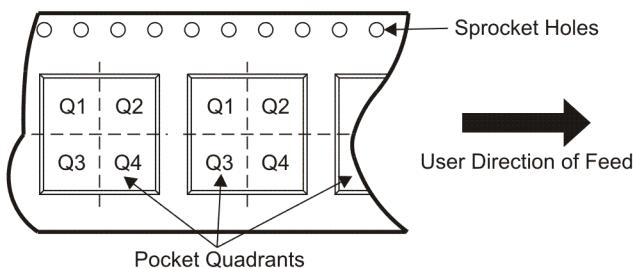
(³) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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TAPE AND REEL INFORMATION
REEL DIMENSIONS

TAPE DIMENSIONS


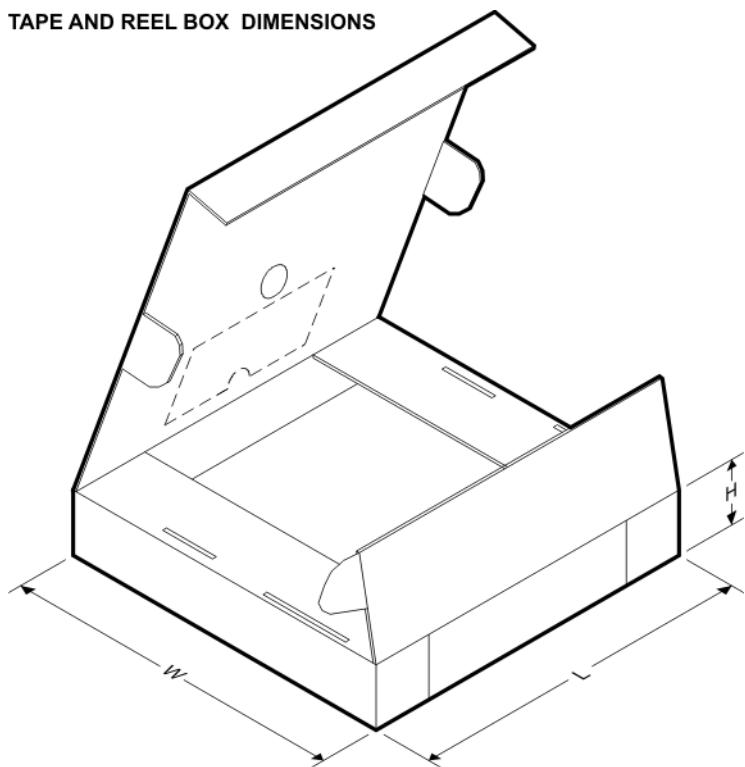
A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
CD4070BM96	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
CD4070BNSR	SO	NS	14	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1
CD4070BPWR	TSSOP	PW	14	2000	330.0	12.4	7.0	5.6	1.6	8.0	12.0	Q1
CD4077BM96	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
CD4077BNSR	SO	NS	14	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1
CD4077BPWR	TSSOP	PW	14	2000	330.0	12.4	7.0	5.6	1.6	8.0	12.0	Q1

TAPE AND REEL BOX DIMENSIONS



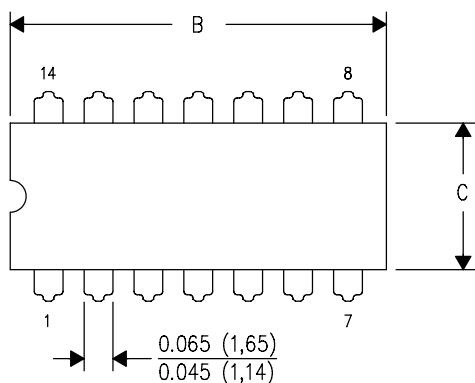
*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
CD4070BM96	SOIC	D	14	2500	346.0	346.0	33.0
CD4070BNSR	SO	NS	14	2000	346.0	346.0	33.0
CD4070BPWR	TSSOP	PW	14	2000	346.0	346.0	29.0
CD4077BM96	SOIC	D	14	2500	346.0	346.0	33.0
CD4077BNSR	SO	NS	14	2000	346.0	346.0	33.0
CD4077BPWR	TSSOP	PW	14	2000	346.0	346.0	29.0

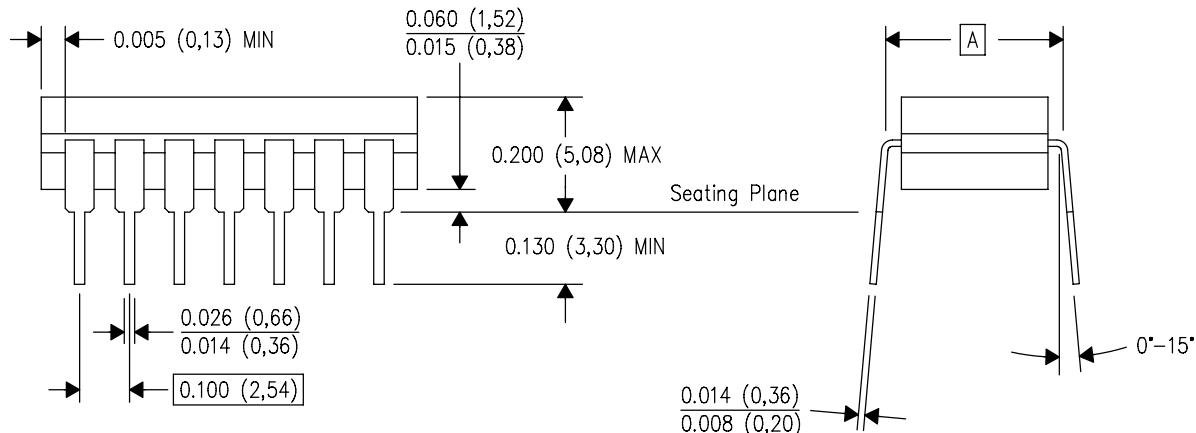
J (R-GDIP-T**)

14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



PINS **\nDIM	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)



4040083/F 03/03

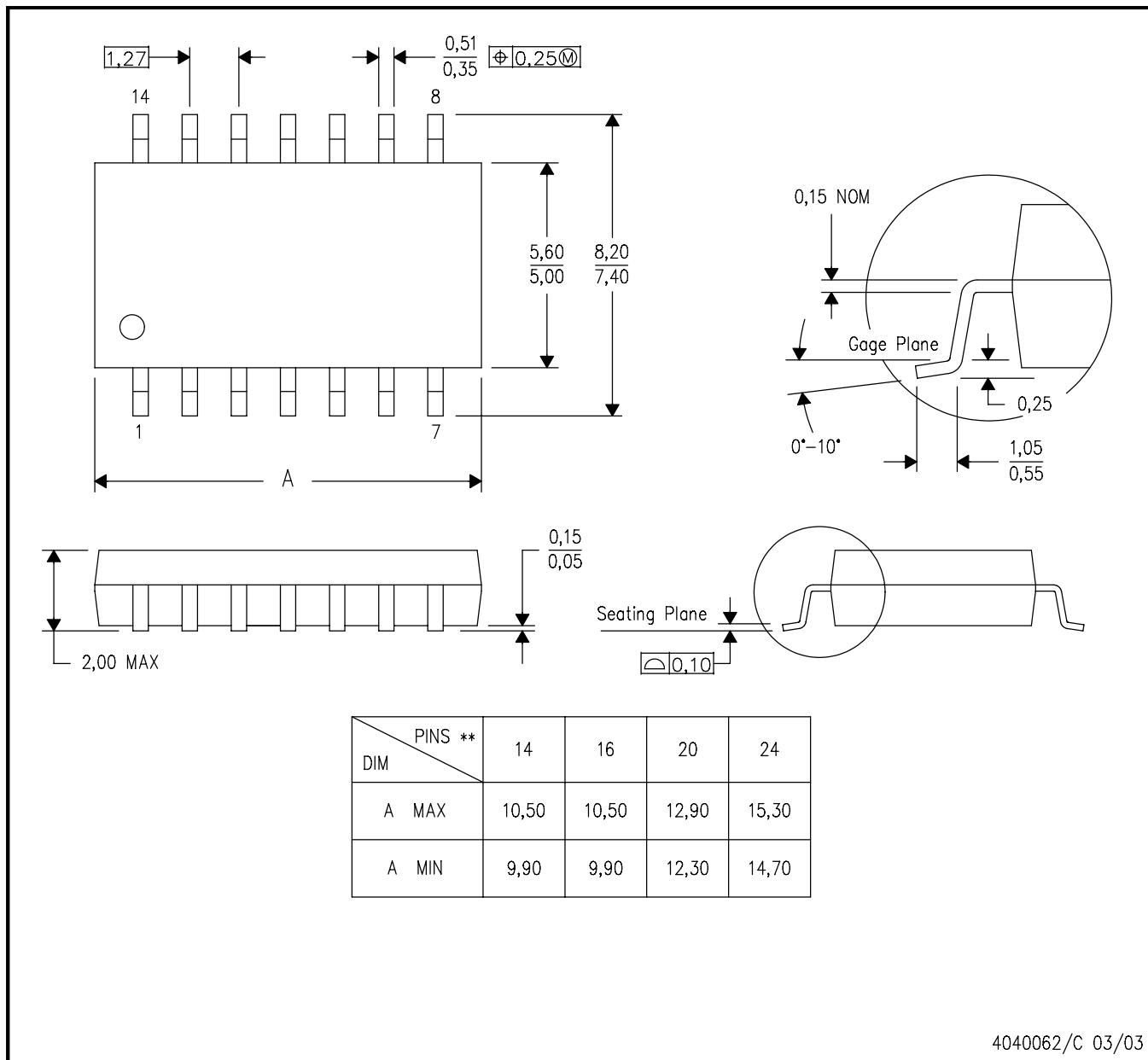
- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. This package is hermetically sealed with a ceramic lid using glass frit.
 - D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
 - E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

MECHANICAL DATA

NS (R-PDSO-G)**

14-PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE

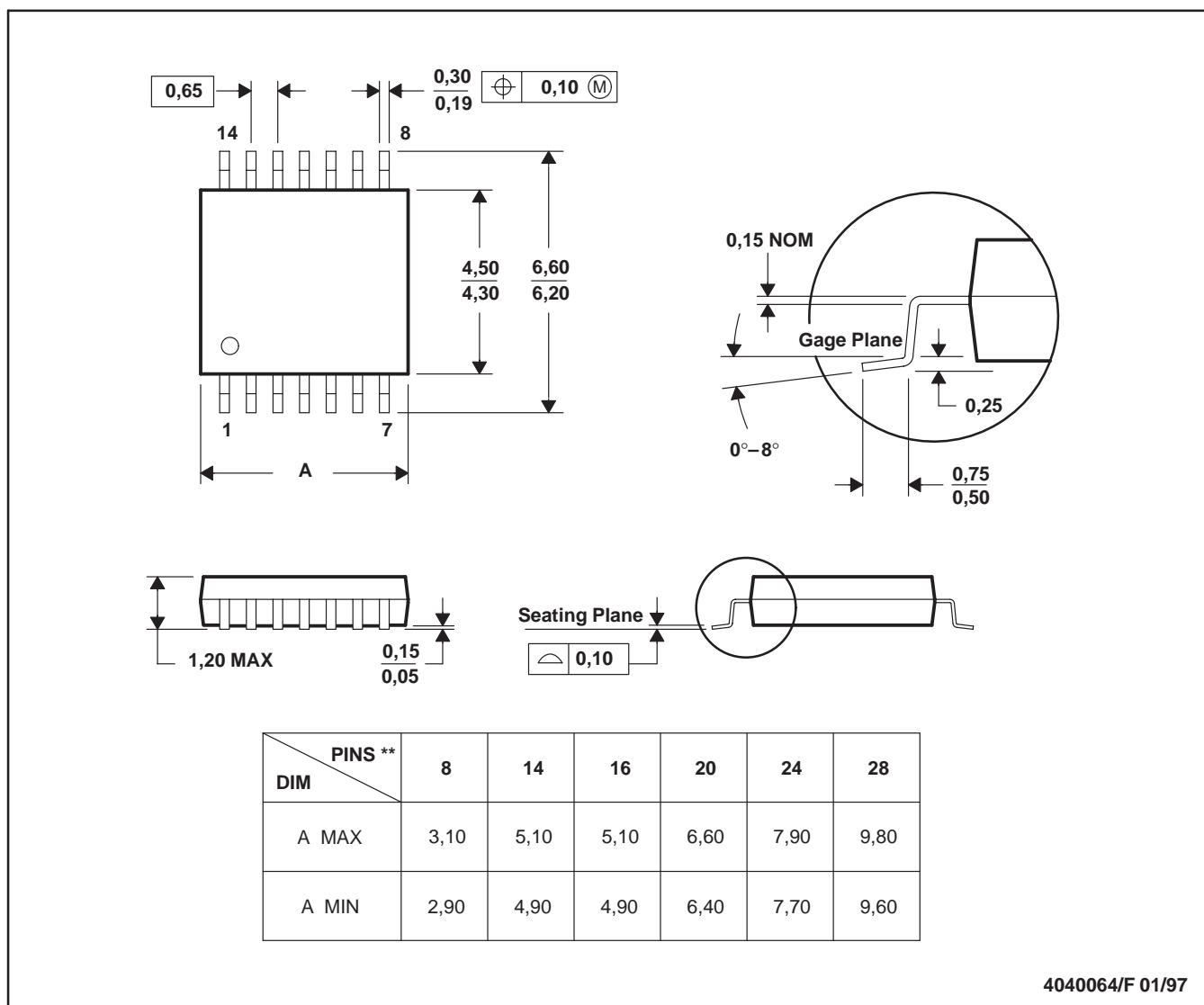


- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

PW (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

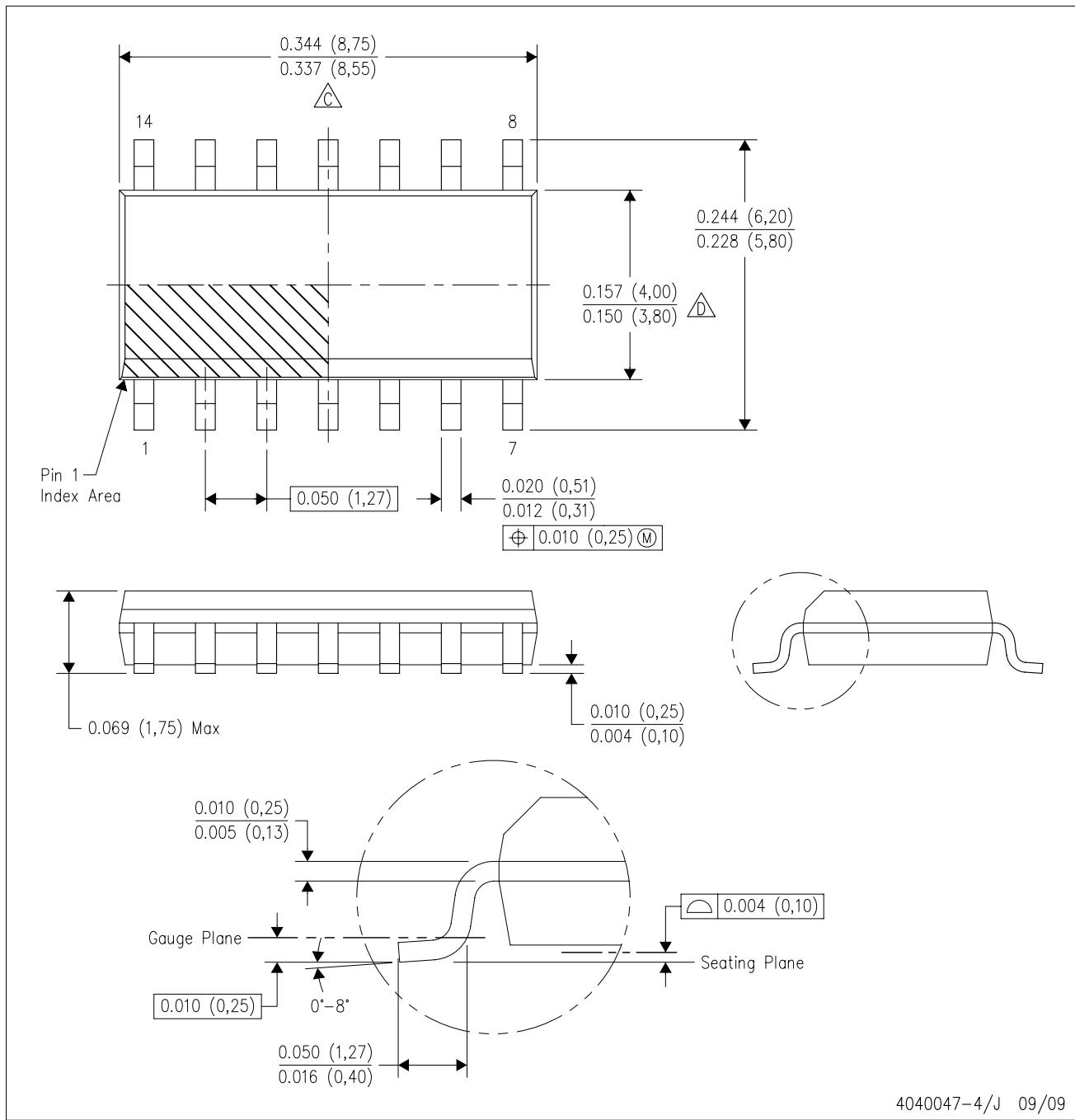
14 PINS SHOWN



- NOTES:
- All linear dimensions are in millimeters.
 - This drawing is subject to change without notice.
 - Body dimensions do not include mold flash or protrusion not to exceed 0,15.
 - Falls within JEDEC MO-153

D (R-PDSO-G14)

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

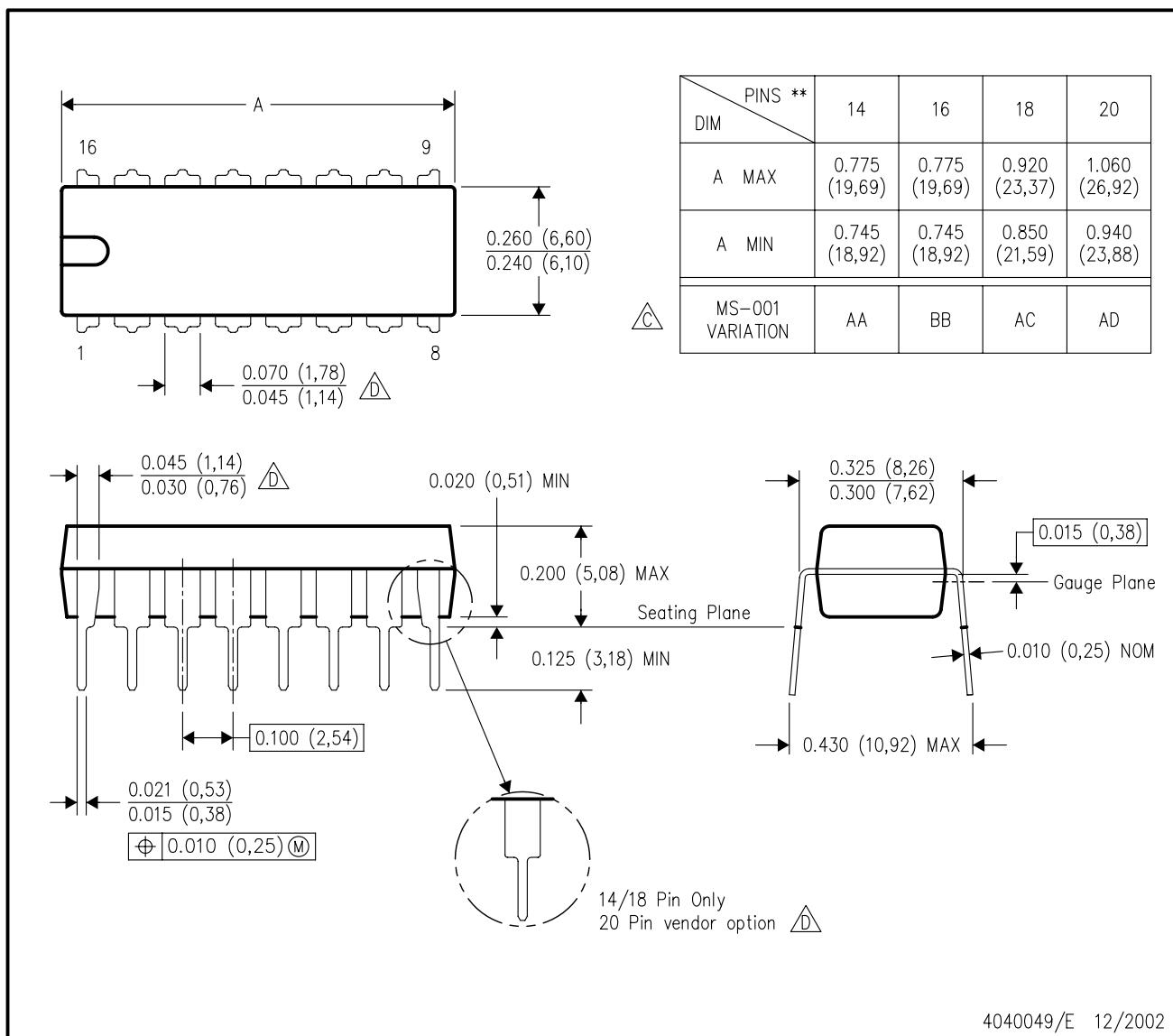
△C Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 (0,15) per end.

△D Body width does not include interlead flash. Interlead flash shall not exceed .017 (0,43) per side.
E. Reference JEDEC MS-012 variation AB.

N (R-PDIP-T**)

16 PINS SHOWN

PLASTIC DUAL-IN-LINE PACKAGE



4040049/E 12/2002

NOTES: A. All linear dimensions are in inches (millimeters).
 B. This drawing is subject to change without notice.

Symbol C: Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).

Symbol D: The 20 pin end lead shoulder width is a vendor option, either half or full width.

PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package Pins	Package qty Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
CD4070BE	Active	Production	PDIP (N) 14	25 TUBE	Yes	NIPDAU	N/A for Pkg Type	-55 to 125	CD4070BE
CD4070BE.A	Active	Production	PDIP (N) 14	25 TUBE	Yes	NIPDAU	N/A for Pkg Type	-55 to 125	CD4070BE
CD4070BEE4	Active	Production	PDIP (N) 14	25 TUBE	Yes	NIPDAU	N/A for Pkg Type	-55 to 125	CD4070BE
CD4070BF	Active	Production	CDIP (J) 14	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	CD4070BF
CD4070BF.A	Active	Production	CDIP (J) 14	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	CD4070BF
CD4070BF3A	Active	Production	CDIP (J) 14	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	CD4070BF3A
CD4070BF3A.A	Active	Production	CDIP (J) 14	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	CD4070BF3A
CD4070BM	Obsolete	Production	SOIC (D) 14	-	-	Call TI	Call TI	-55 to 125	CD4070BM
CD4070BM96	Active	Production	SOIC (D) 14	2500 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-55 to 125	CD4070BM
CD4070BM96.A	Active	Production	SOIC (D) 14	2500 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-55 to 125	CD4070BM
CD4070BM96E4	Active	Production	SOIC (D) 14	2500 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-55 to 125	CD4070BM
CD4070BMT	Obsolete	Production	SOIC (D) 14	-	-	Call TI	Call TI	-55 to 125	CD4070BM
CD4070BNSR	Active	Production	SOP (NS) 14	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-55 to 125	CD4070B
CD4070BNSR.A	Active	Production	SOP (NS) 14	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-55 to 125	CD4070B
CD4070BPW	Obsolete	Production	TSSOP (PW) 14	-	-	Call TI	Call TI	-55 to 125	CM070B
CD4070BPWR	Active	Production	TSSOP (PW) 14	2000 LARGE T&R	Yes	NIPDAU SN	Level-1-260C-UNLIM	-55 to 125	CM070B
CD4070BPWR.A	Active	Production	TSSOP (PW) 14	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-55 to 125	CM070B
CD4077BE	Active	Production	PDIP (N) 14	25 TUBE	Yes	NIPDAU	N/A for Pkg Type	-55 to 125	CD4077BE
CD4077BE.A	Active	Production	PDIP (N) 14	25 TUBE	Yes	NIPDAU	N/A for Pkg Type	-55 to 125	CD4077BE
CD4077BF	Active	Production	CDIP (J) 14	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	CD4077BF
CD4077BF.A	Active	Production	CDIP (J) 14	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	CD4077BF
CD4077BF3A	Active	Production	CDIP (J) 14	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	CD4077BF3A
CD4077BF3A.A	Active	Production	CDIP (J) 14	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	CD4077BF3A
CD4077BM	Obsolete	Production	SOIC (D) 14	-	-	Call TI	Call TI	-55 to 125	CD4077BM
CD4077BM96	Active	Production	SOIC (D) 14	2500 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-55 to 125	CD4077BM
CD4077BM96.A	Active	Production	SOIC (D) 14	2500 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-55 to 125	CD4077BM
CD4077BMT	Obsolete	Production	SOIC (D) 14	-	-	Call TI	Call TI	-55 to 125	CD4077BM
CD4077BNSR	Active	Production	SOP (NS) 14	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-55 to 125	CD4077B
CD4077BNSR.A	Active	Production	SOP (NS) 14	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-55 to 125	CD4077B

Orderable part number	Status (1)	Material type (2)	Package Pins	Package qty Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
CD4077BPW	Active	Production	TSSOP (PW) 14	90 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-55 to 125	CM077B
CD4077BPW.A	Active	Production	TSSOP (PW) 14	90 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-55 to 125	CM077B
JM38510/17203BCA	Active	Production	CDIP (J) 14	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	JM38510/ 17203BCA
JM38510/17203BCA.A	Active	Production	CDIP (J) 14	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	JM38510/ 17203BCA
M38510/17203BCA	Active	Production	CDIP (J) 14	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	JM38510/ 17203BCA

⁽¹⁾ **Status:** For more details on status, see our [product life cycle](#).

⁽²⁾ **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

⁽³⁾ **RoHS values:** Yes, No, RoHS Exempt. See the [TI RoHS Statement](#) for additional information and value definition.

⁽⁴⁾ **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

⁽⁵⁾ **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

⁽⁶⁾ **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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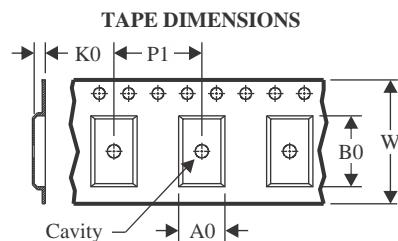
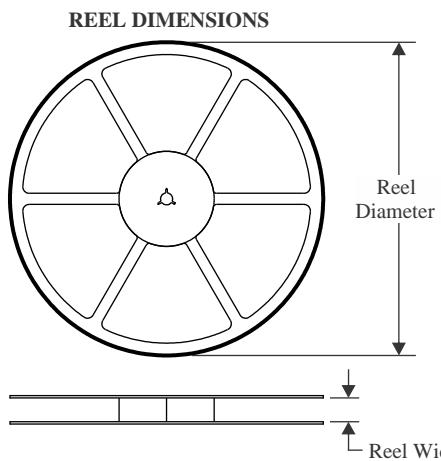
OTHER QUALIFIED VERSIONS OF CD4070B, CD4070B-MIL, CD4077B, CD4077B-MIL :

- Catalog : [CD4070B](#), [CD4077B](#)
- Military : [CD4070B-MIL](#), [CD4077B-MIL](#)

NOTE: Qualified Version Definitions:

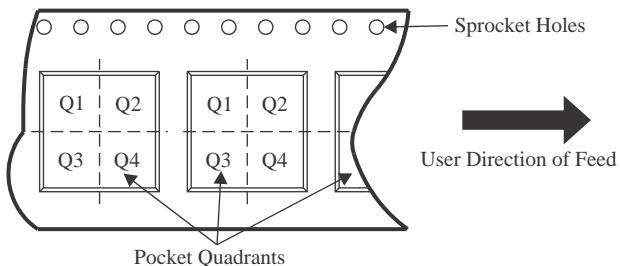
- Catalog - TI's standard catalog product
- Military - QML certified for Military and Defense Applications

TAPE AND REEL INFORMATION



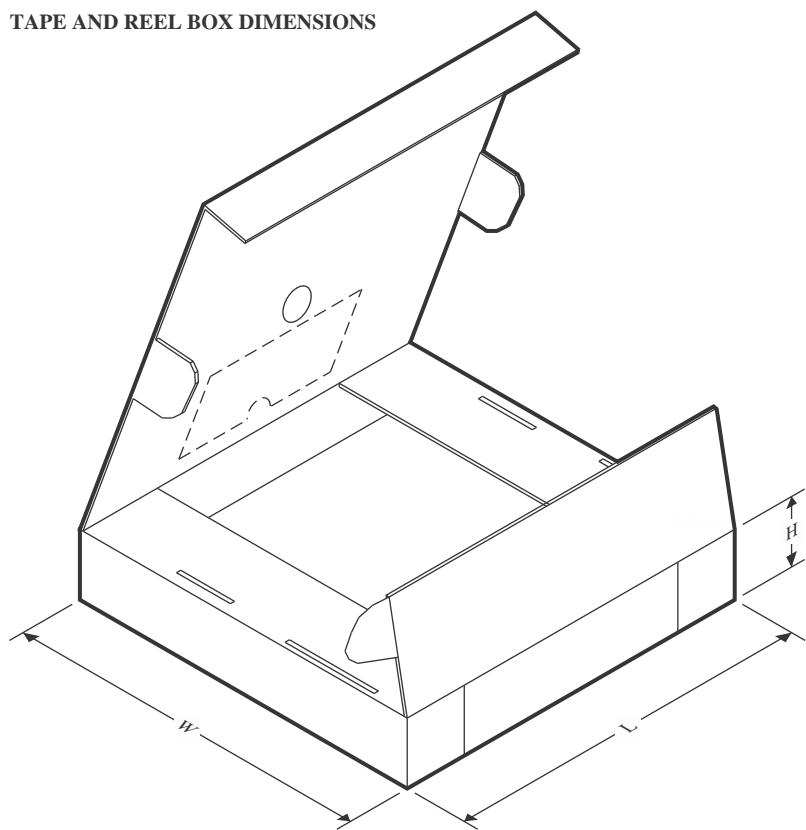
A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



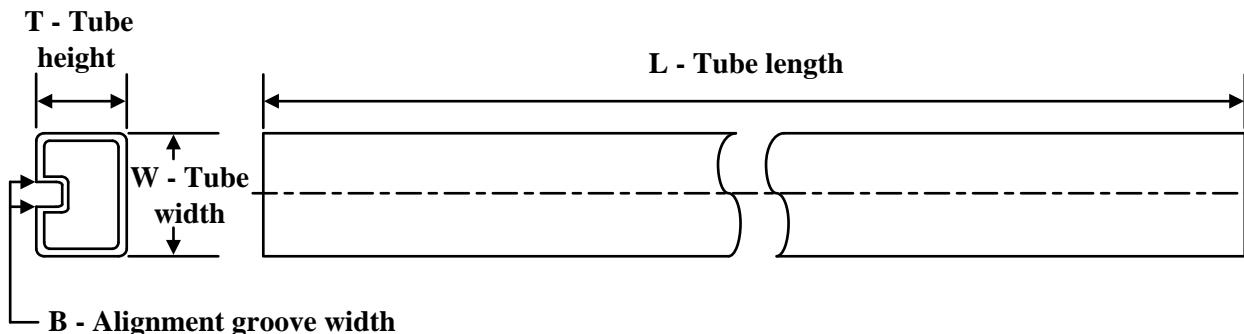
*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
CD4070BM96	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
CD4070BNSR	SOP	NS	14	2000	330.0	16.4	8.1	10.4	2.5	12.0	16.0	Q1
CD4070BPWR	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
CD4077BM96	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
CD4077BNSR	SOP	NS	14	2000	330.0	16.4	8.1	10.4	2.5	12.0	16.0	Q1

TAPE AND REEL BOX DIMENSIONS


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
CD4070BM96	SOIC	D	14	2500	353.0	353.0	32.0
CD4070BNSR	SOP	NS	14	2000	353.0	353.0	32.0
CD4070BPWR	TSSOP	PW	14	2000	356.0	356.0	35.0
CD4077BM96	SOIC	D	14	2500	353.0	353.0	32.0
CD4077BNSR	SOP	NS	14	2000	353.0	353.0	32.0

TUBE


*All dimensions are nominal

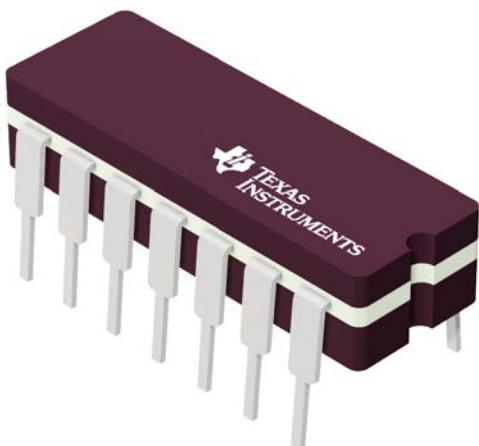
Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (μ m)	B (mm)
CD4070BE	N	PDIP	14	25	506	13.97	11230	4.32
CD4070BE.A	N	PDIP	14	25	506	13.97	11230	4.32
CD4070BEE4	N	PDIP	14	25	506	13.97	11230	4.32
CD4077BE	N	PDIP	14	25	506	13.97	11230	4.32
CD4077BE.A	N	PDIP	14	25	506	13.97	11230	4.32
CD4077BPW	PW	TSSOP	14	90	530	10.2	3600	3.5
CD4077BPW.A	PW	TSSOP	14	90	530	10.2	3600	3.5

GENERIC PACKAGE VIEW

J 14

CDIP - 5.08 mm max height

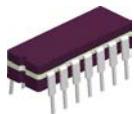
CERAMIC DUAL IN LINE PACKAGE



Images above are just a representation of the package family, actual package may vary.
Refer to the product data sheet for package details.

4040083-5/G

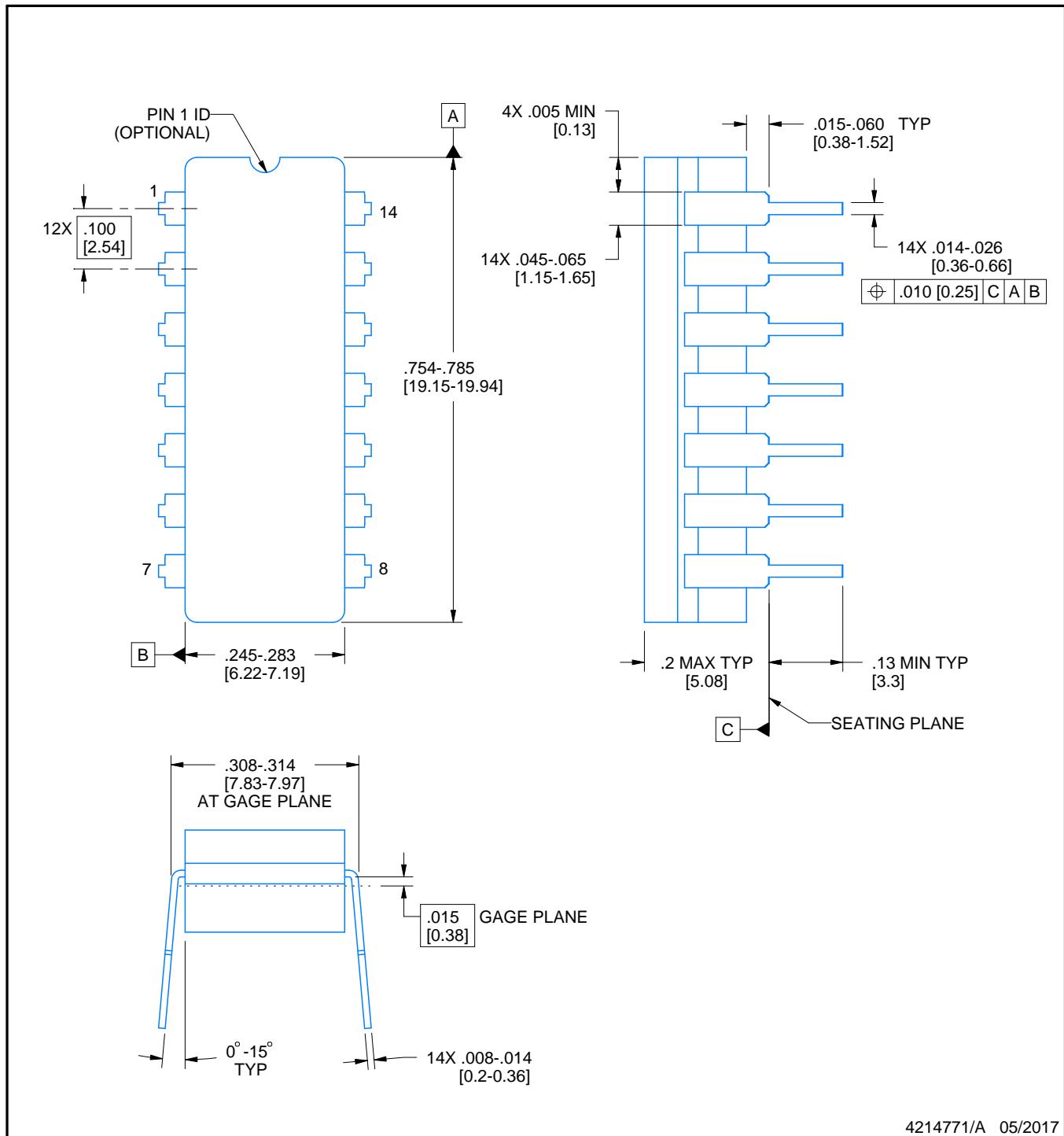
J0014A



PACKAGE OUTLINE

CDIP - 5.08 mm max height

CERAMIC DUAL IN LINE PACKAGE



4214771/A 05/2017

NOTES:

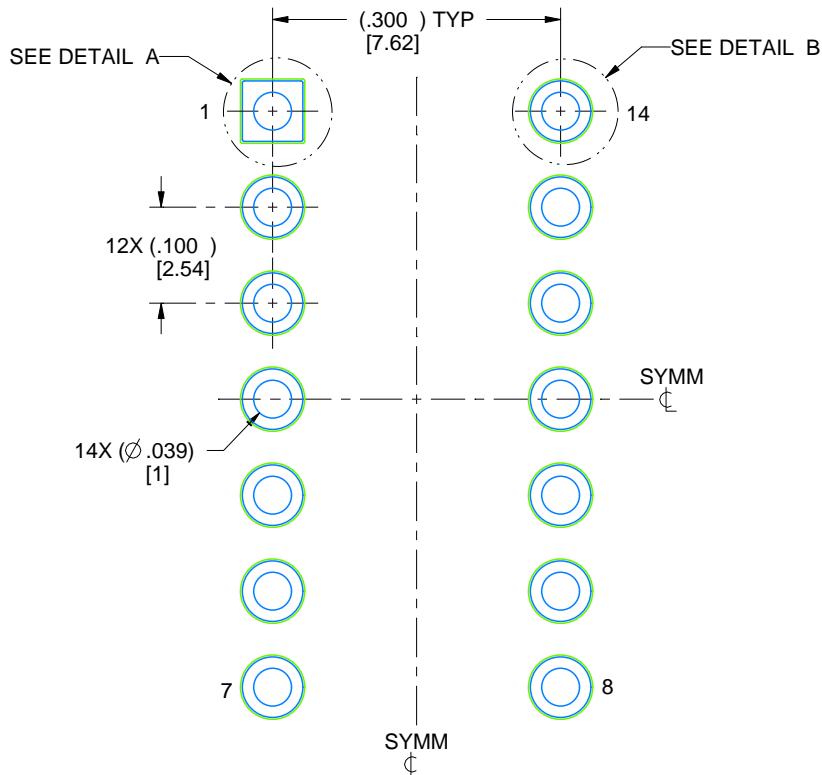
1. All controlling linear dimensions are in inches. Dimensions in brackets are in millimeters. Any dimension in brackets or parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This package is hermetically sealed with a ceramic lid using glass frit.
4. Index point is provided on cap for terminal identification only and on press ceramic glass frit seal only.
5. Falls within MIL-STD-1835 and GDIP1-T14.

EXAMPLE BOARD LAYOUT

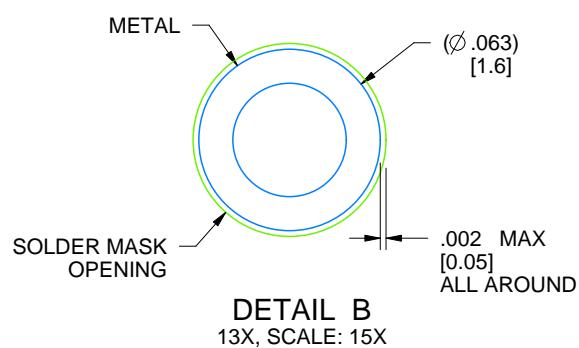
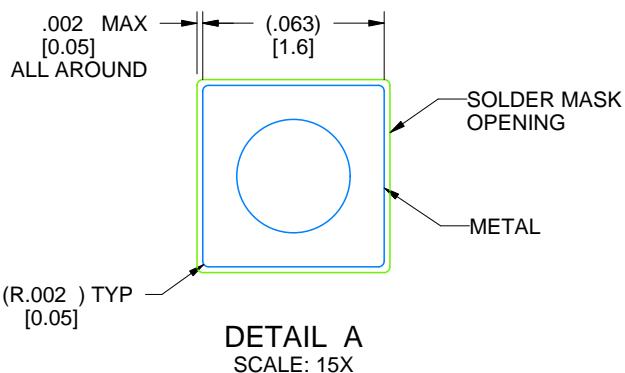
J0014A

CDIP - 5.08 mm max height

CERAMIC DUAL IN LINE PACKAGE



LAND PATTERN EXAMPLE
NON-SOLDER MASK DEFINED
SCALE: 5X

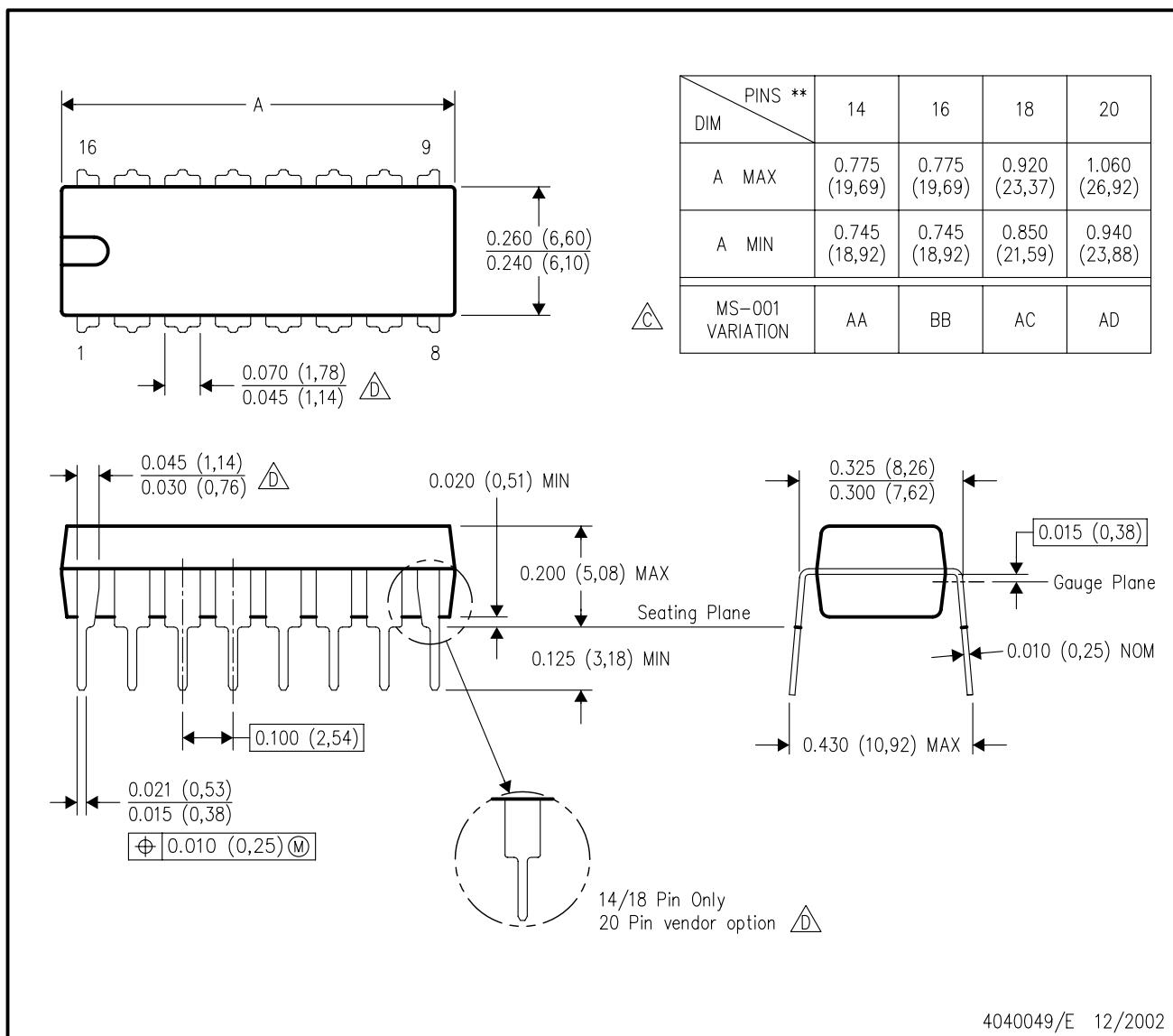


4214771/A 05/2017

N (R-PDIP-T**)

16 PINS SHOWN

PLASTIC DUAL-IN-LINE PACKAGE



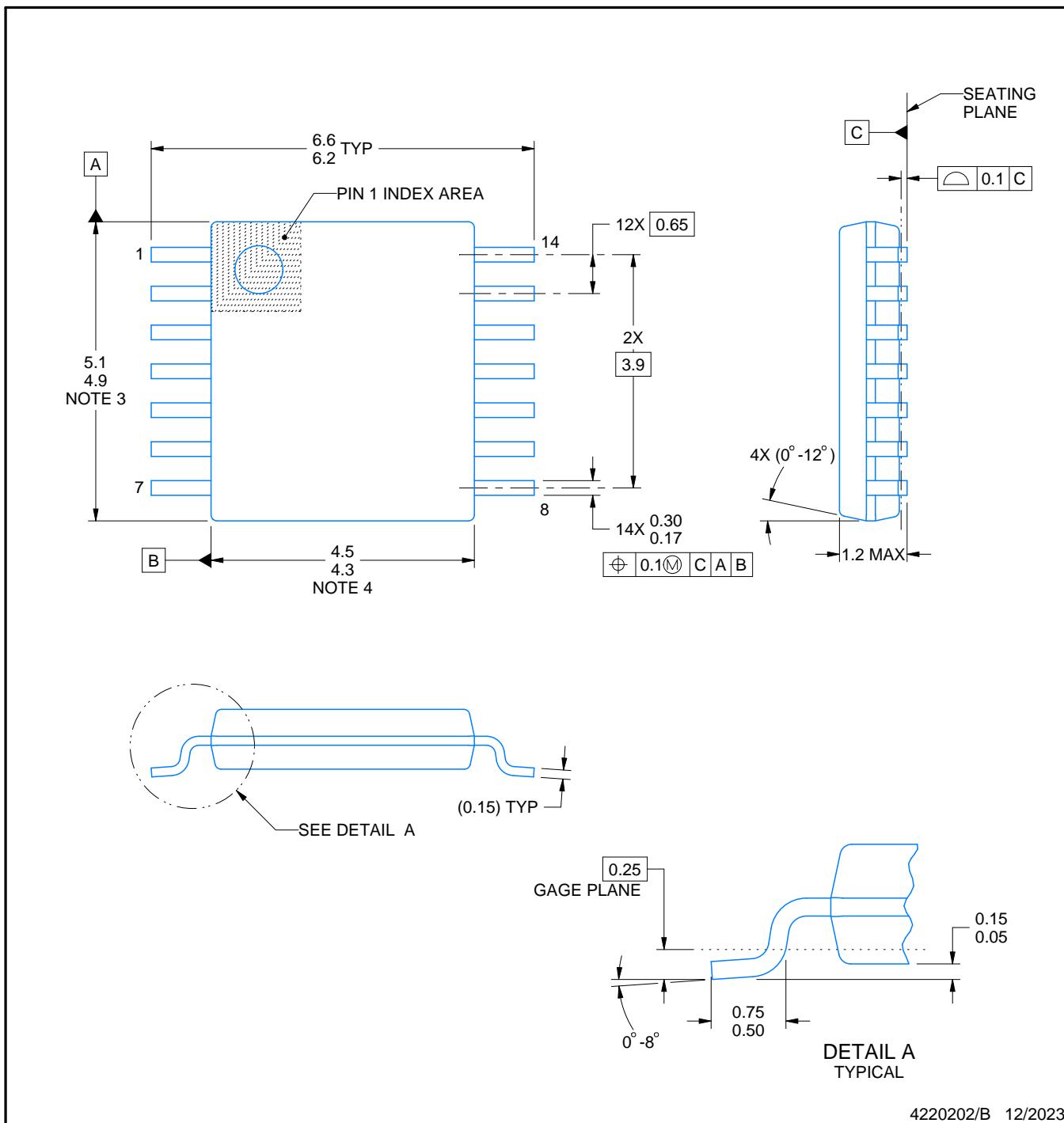
PACKAGE OUTLINE

PW0014A



TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



4220202/B 12/2023

NOTES:

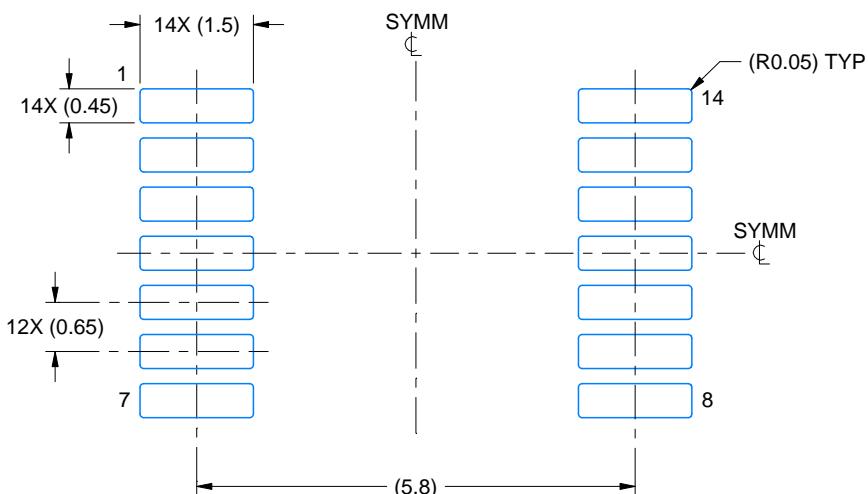
- All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
- This drawing is subject to change without notice.
- This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
- This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
- Reference JEDEC registration MO-153.

EXAMPLE BOARD LAYOUT

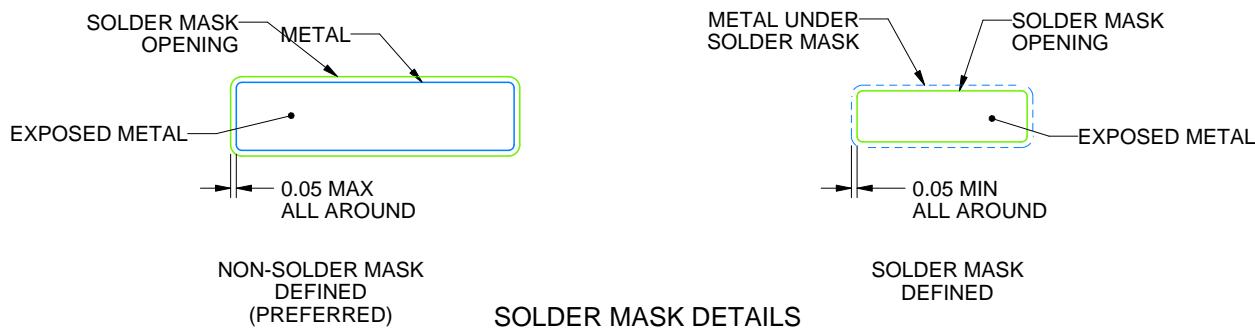
PW0014A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE: 10X



4220202/B 12/2023

NOTES: (continued)

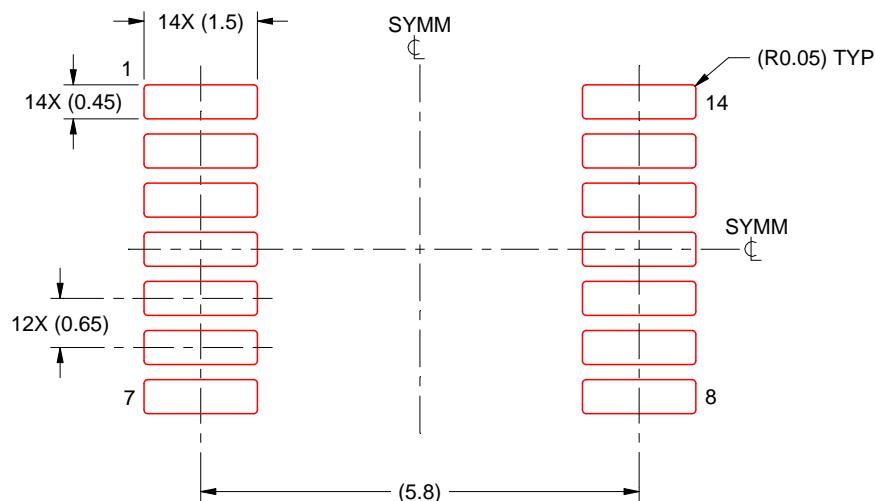
6. Publication IPC-7351 may have alternate designs.
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

PW0014A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE: 10X

4220202/B 12/2023

NOTES: (continued)

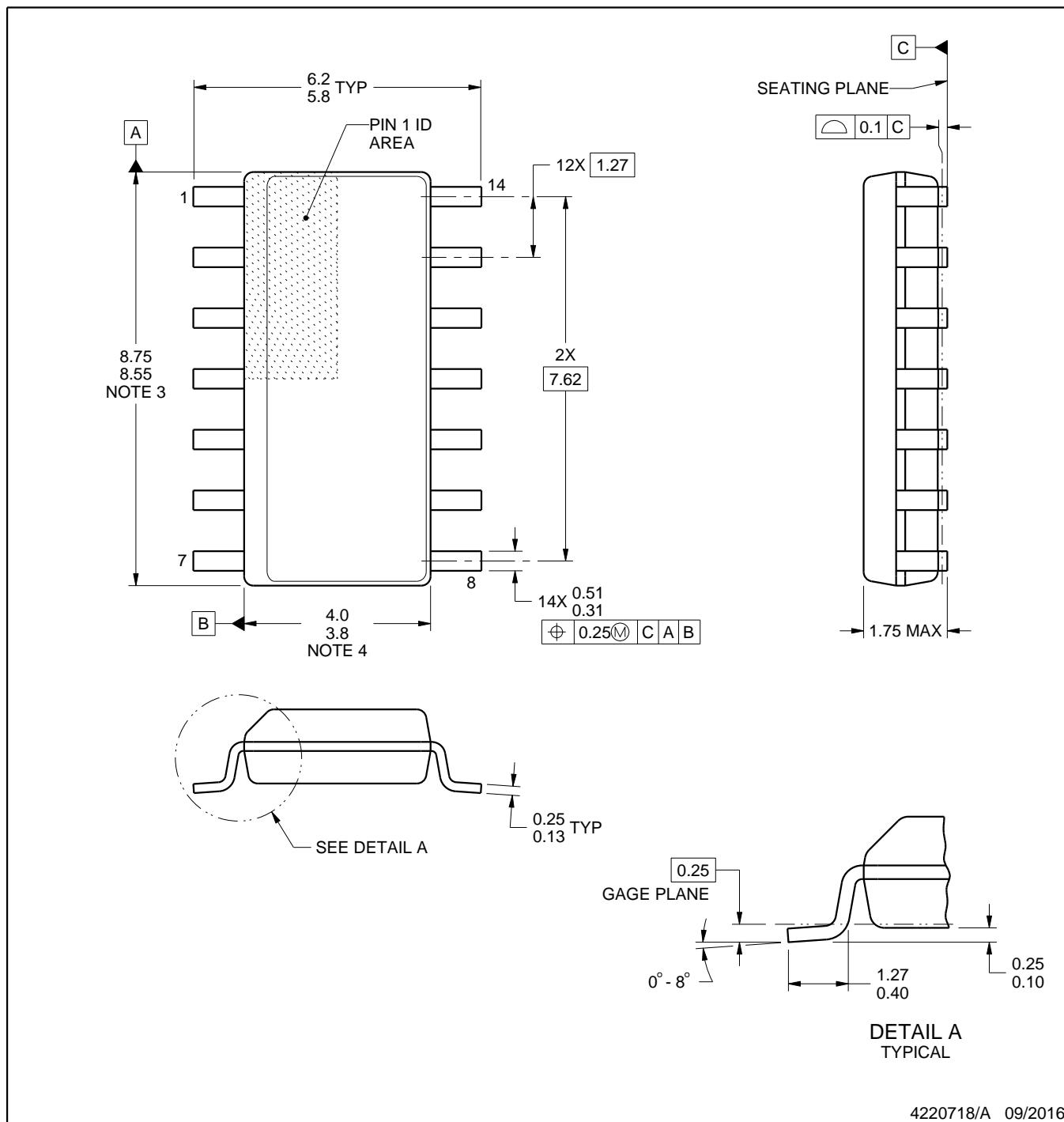
8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

PACKAGE OUTLINE

D0014A

SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT



NOTES:

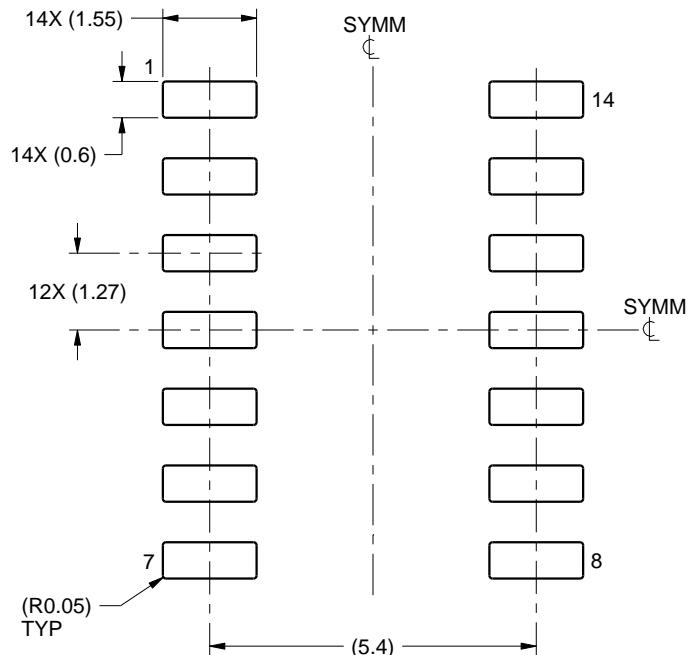
- All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
- This drawing is subject to change without notice.
- This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm, per side.
- This dimension does not include interlead flash. Interlead flash shall not exceed 0.43 mm, per side.
- Reference JEDEC registration MS-012, variation AB.

EXAMPLE BOARD LAYOUT

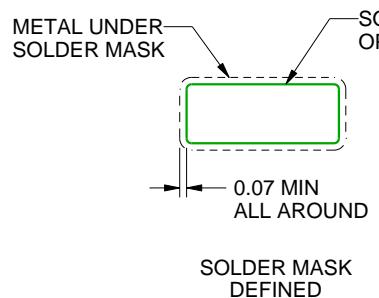
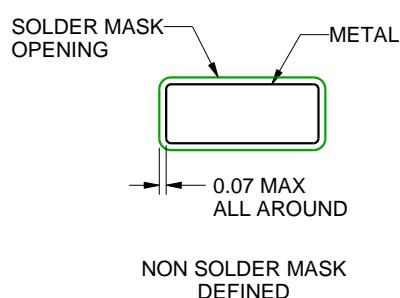
D0014A

SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT



LAND PATTERN EXAMPLE
SCALE:8X



SOLDER MASK DETAILS

4220718/A 09/2016

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

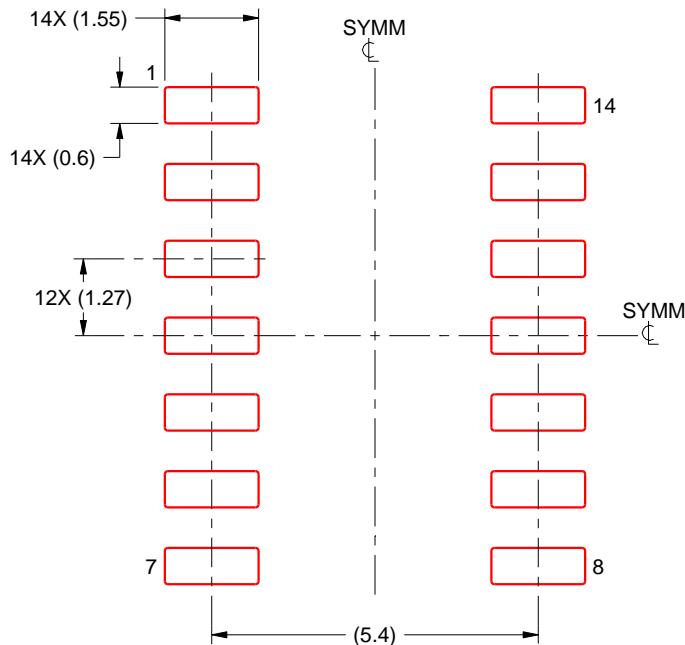
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

D0014A

SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE:8X

4220718/A 09/2016

NOTES: (continued)

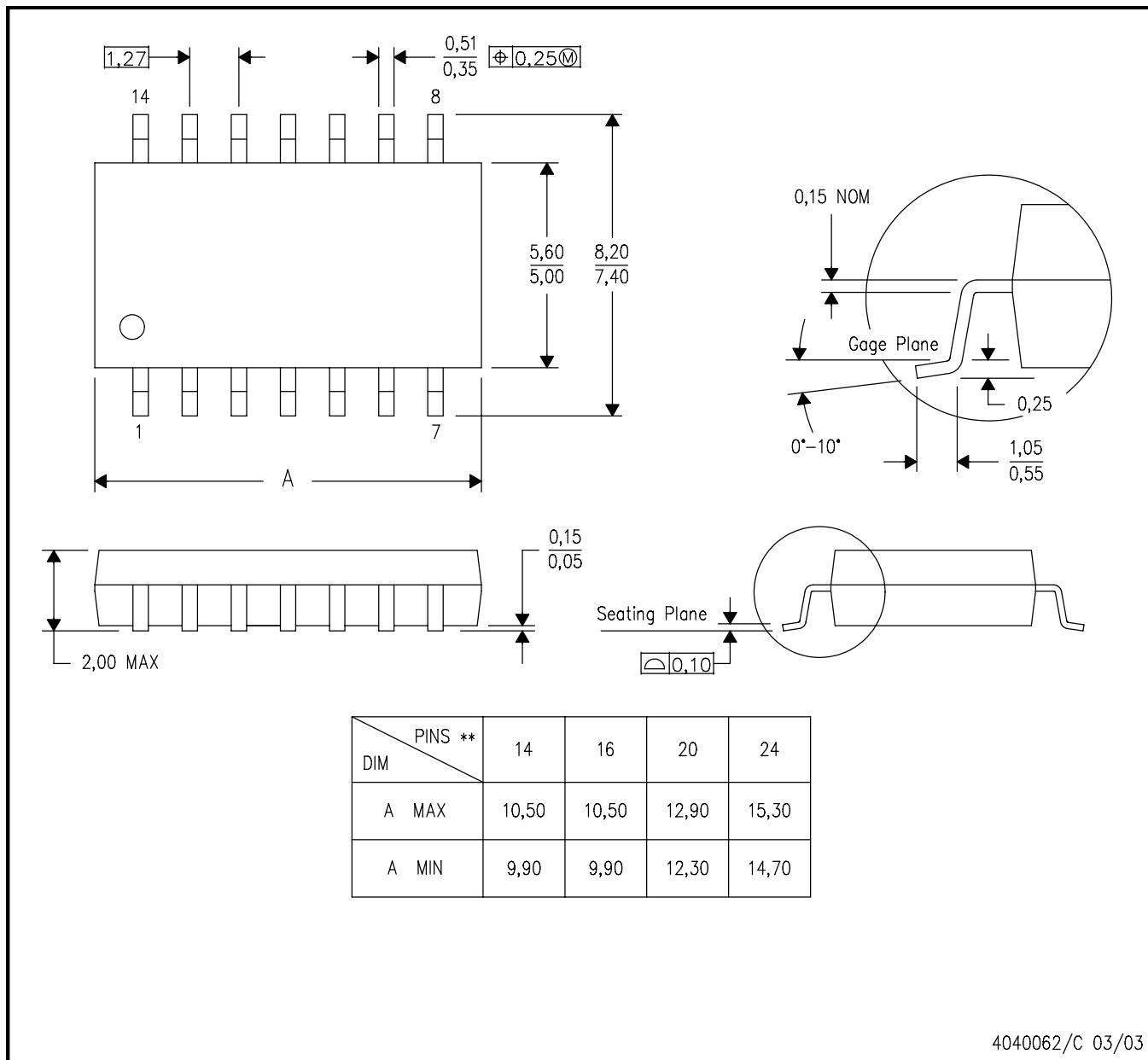
8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

MECHANICAL DATA

NS (R-PDSO-G)**

14-PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

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